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(12) **United States Design Patent** (10) **Patent No.:** **US D889,421 S**
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(54) **LIGHT EMITTING DIODE PACKAGE**

H01L 33/48; H01L 33/483; H01L 33/486;
F21S 43/14; F21S 43/145; F21S 43/15;
F21S 43/20

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See application file for complete search history.

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(73) Assignee: **Seoul Semiconductor Co., Ltd.**, Ansan-si (KR)

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
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D26/2, 25, 35, 74, 80, 81
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;

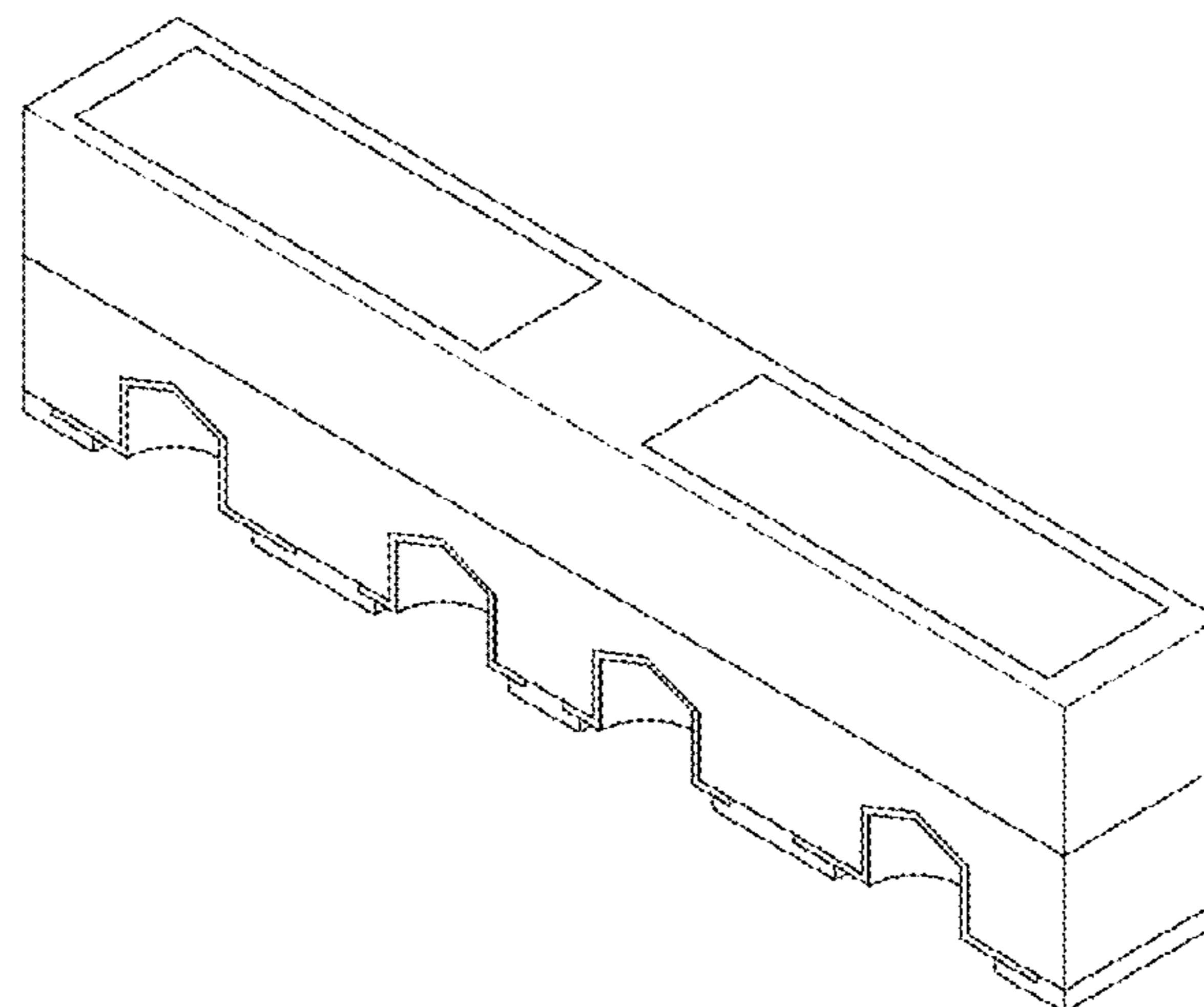
(57) **CLAIM**

The ornamental design for light emitting diode package, as shown and described.

DESCRIPTION

- 1. Light emitting diode package
- 1.1 : Perspective
- 1.2 : Front
- 1.3 : Back
- 1.4 : Left
- 1.5 : Right
- 1.6 : Top

(Continued)



1.7 : Bottom

1 Claim, 7 Drawing Sheets

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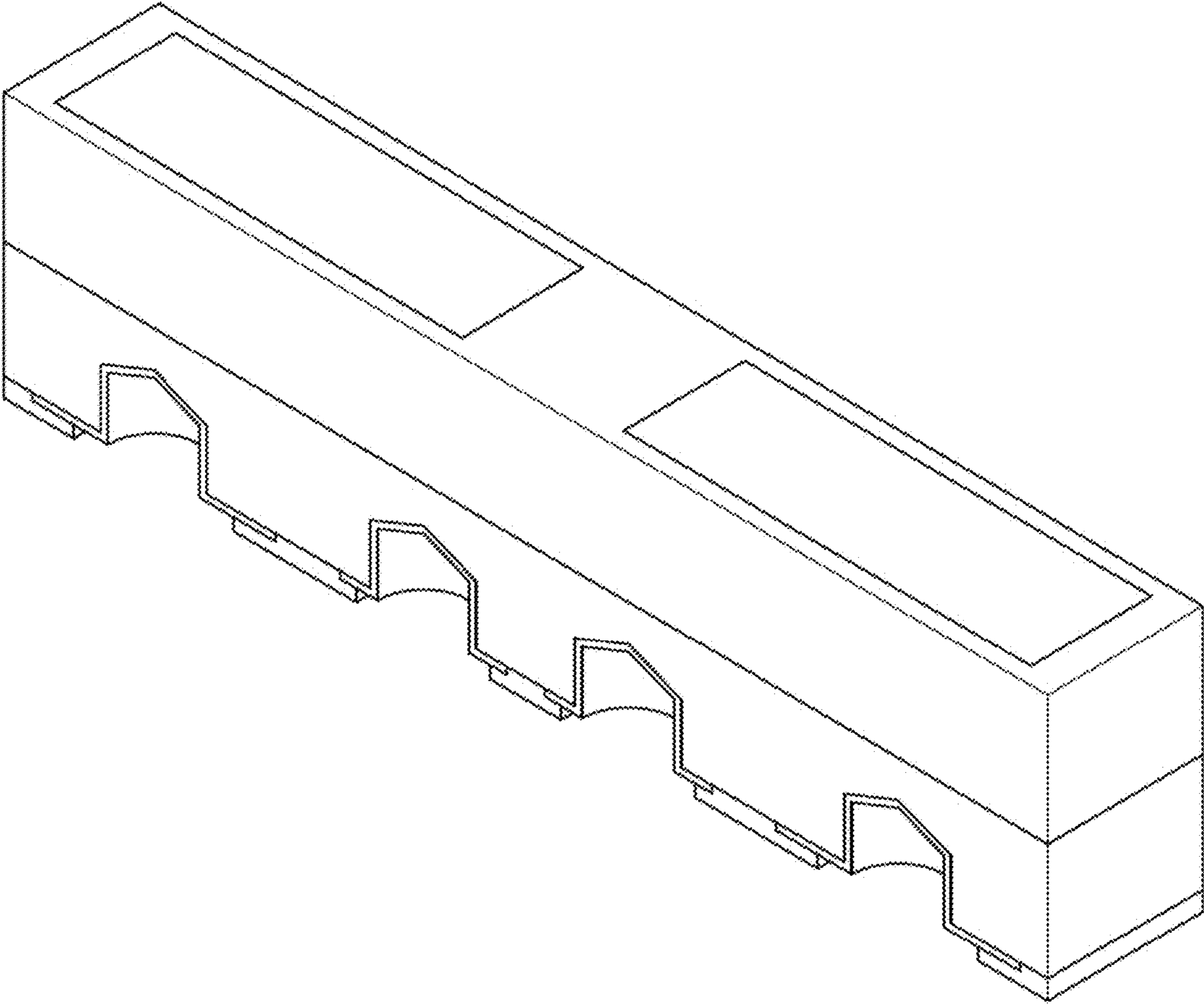
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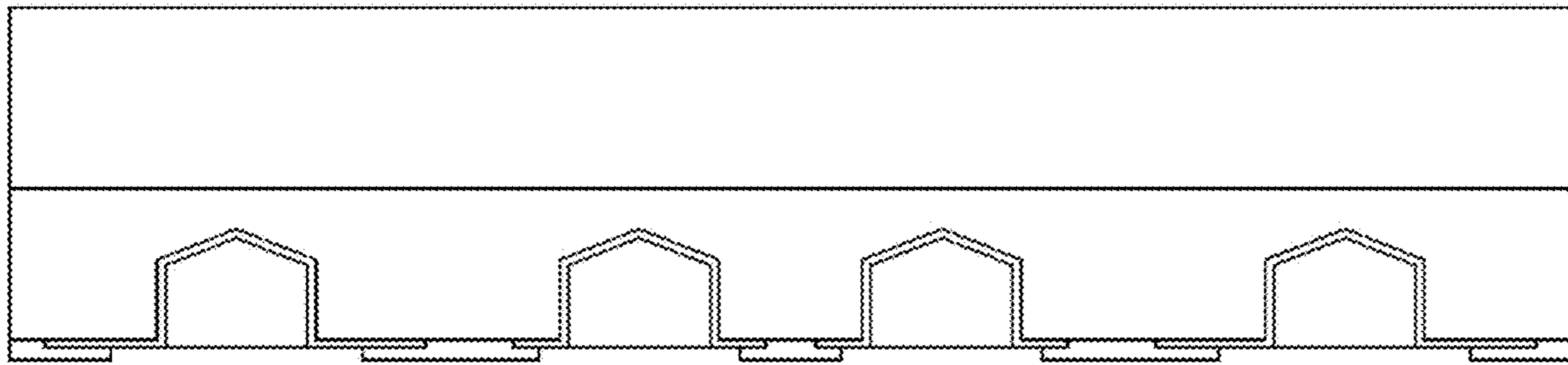
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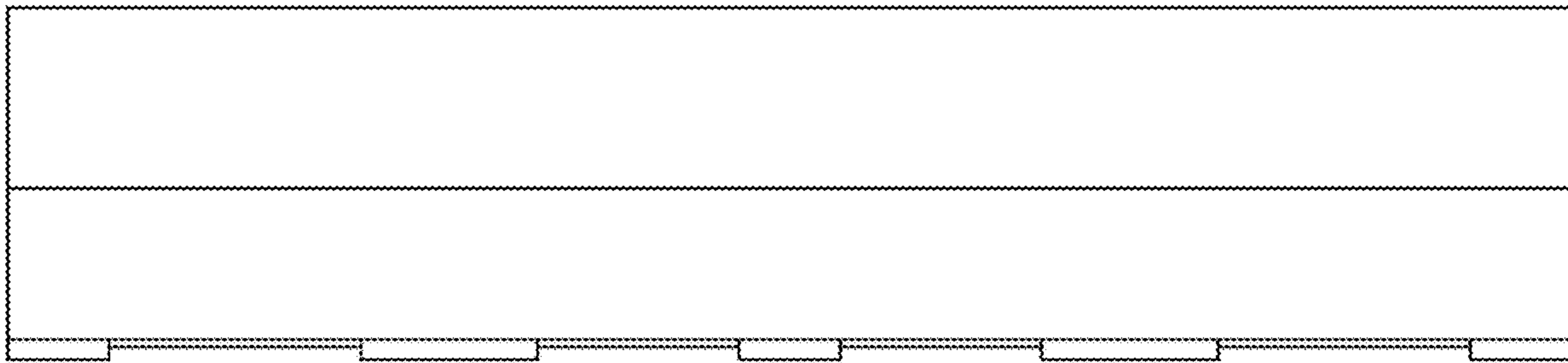
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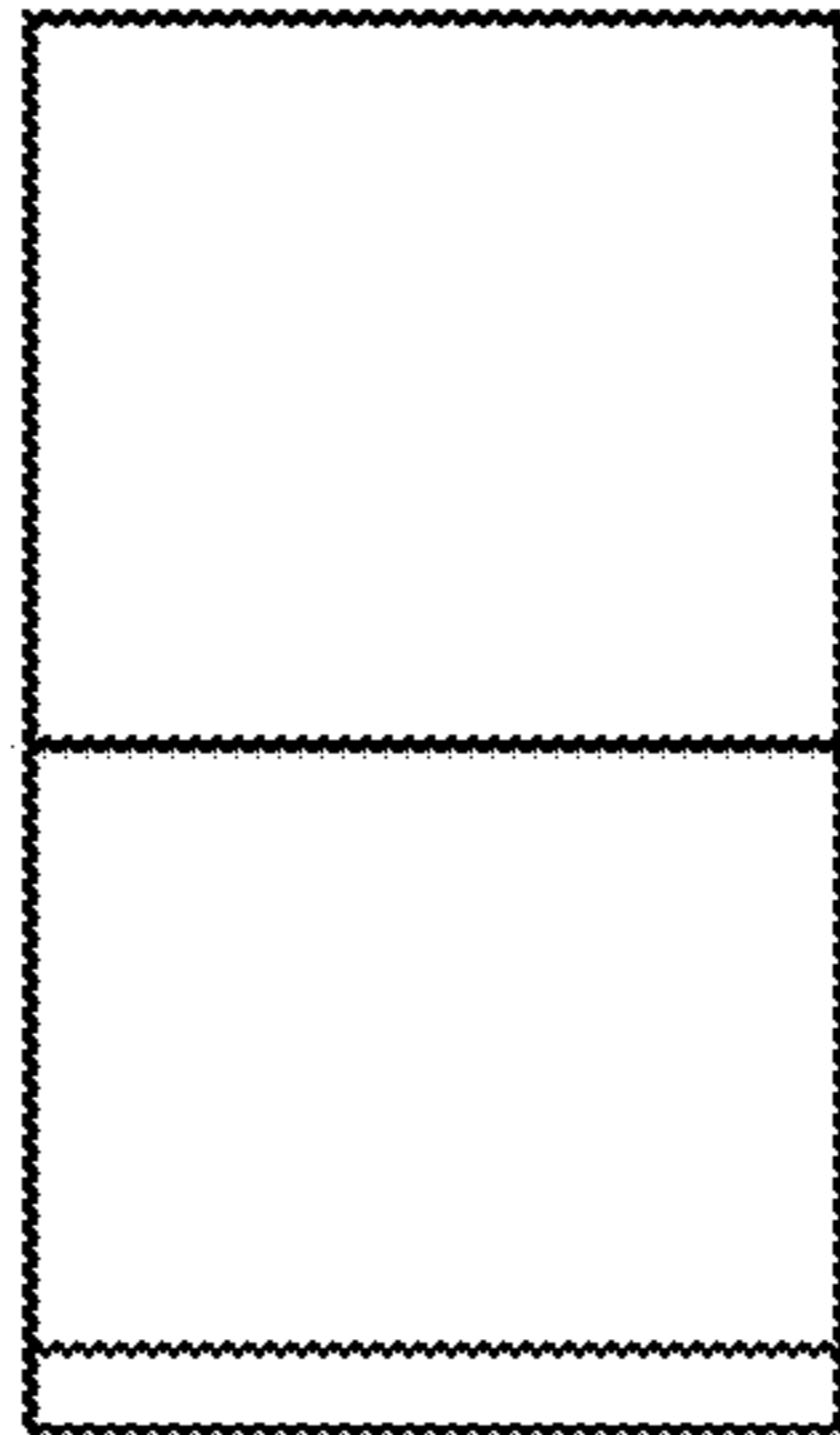
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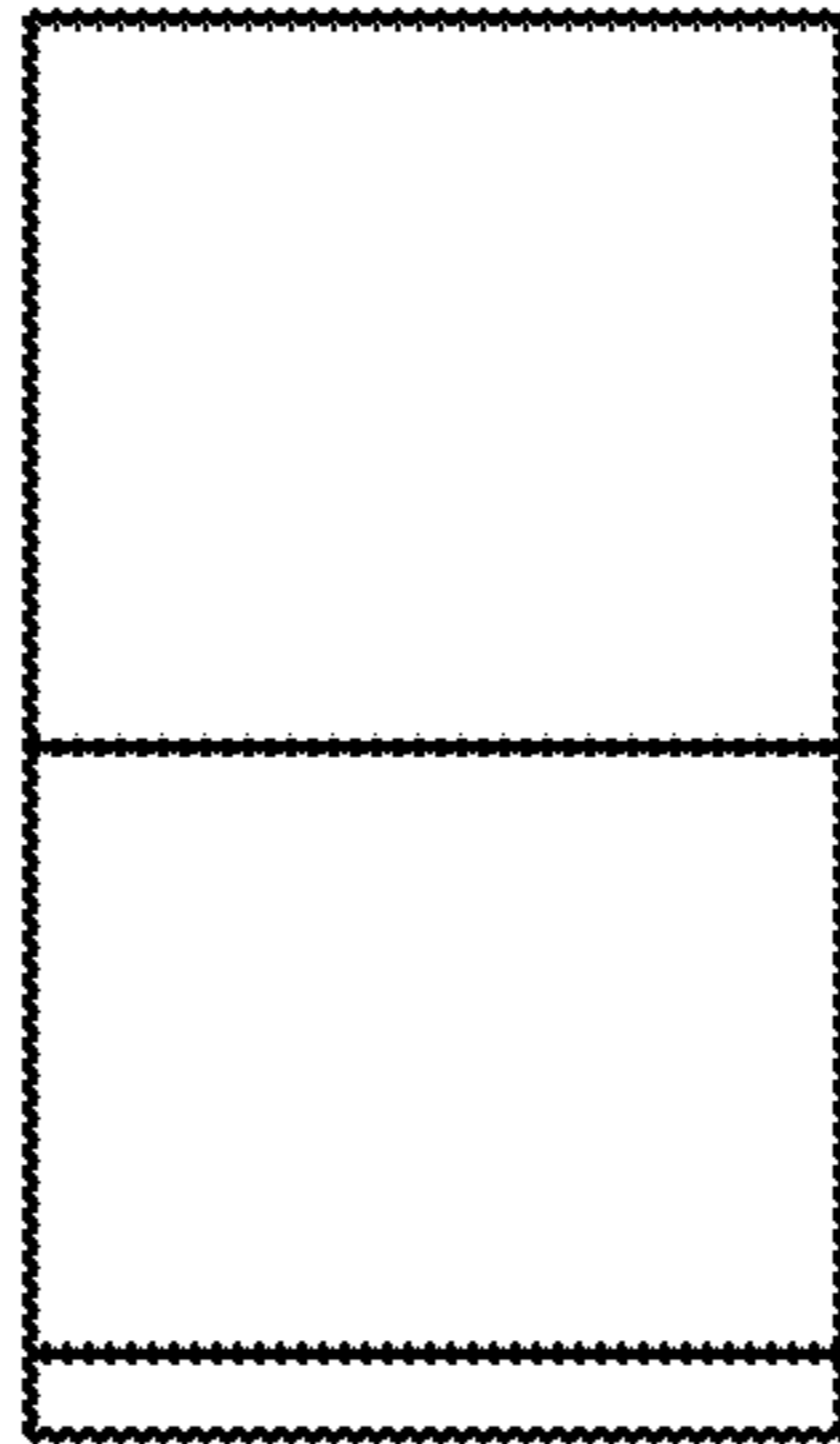
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1.6



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